

## General Description

The MY10N15D is silicon N-channel Enhanced V<sub>D</sub>MOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. applications.

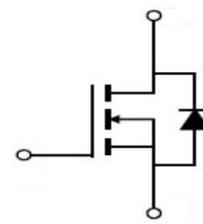
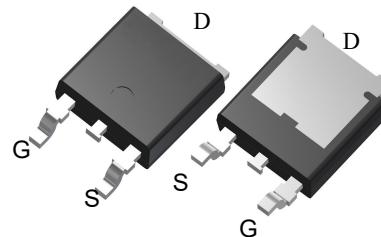


## Features

V <sub>DSS</sub>	150	V
I <sub>D</sub>	10	A
P <sub>D</sub> (T <sub>C</sub> =25°C)	46	W
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V)	0.28	Ω

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY10N15D	TO-252-2L	280KNH	2500

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	150	V
Continuous Drain Current	I <sub>D</sub>	10	A
Pulsed Drain Current	I <sub>DM</sub>	20	A
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Single Pulse Avalanche Energy	E <sub>AS</sub>	45	mJ
Avalanche Current	I <sub>AR</sub>	3	A
Repetitive Avalanche Energy	E <sub>AR</sub>	3.2	mJ
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	46	W
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	2.7	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	60	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

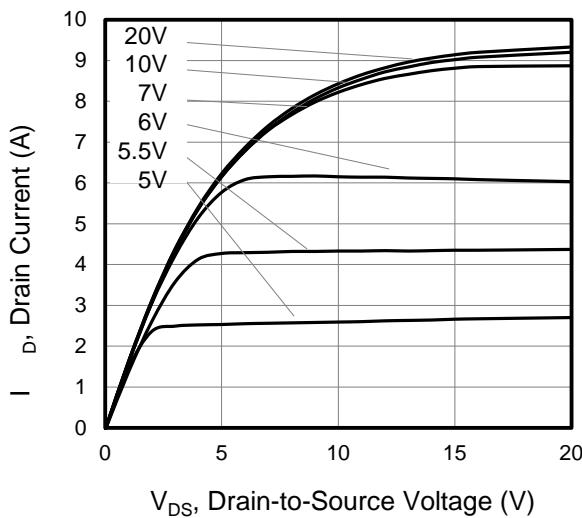
**Electrical Characteristics** at  $T_J=25\text{ }^{\circ}\text{C}$  unless otherwise specified

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	150	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25\text{ }^{\circ}\text{C}$	--	--	5	$\mu\text{A}$
		$V_{\text{DS}} = 120\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125\text{ }^{\circ}\text{C}$	--	--	100	
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.5	2.5	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 8\text{A}$	--	0.23	0.28	$\Omega$
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V},$ $V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	228	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	48	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	17	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 120\text{V}, I_D = 5.0\text{A},$ $V_{\text{GS}} = 10\text{V}$	--	18	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	1.5	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	9.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 100\text{V}, I_D = 5.0\text{A},$ $R_G = 25\text{ }\Omega$	--	10	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	19	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	43	--	
Turn-off Fall Time	$t_f$		--	32	--	
Continuous Body Diode Current	$I_s$	$T_C = 25\text{ }^{\circ}\text{C}$	--	--	5	$\text{A}$
Pulsed Diode Forward Current	$I_{\text{SM}}$		--	--	20	
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25\text{ }^{\circ}\text{C}, I_{\text{SD}} = 5\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{GS}} = 0\text{V}, I_s = 5\text{A},$ $dI_F/dt = 100\text{A}/\mu\text{s}$	--	160	--	$\text{ns}$
Reverse Recovery Charge	$Q_{\text{rr}}$		--	1.5	--	$\mu\text{C}$

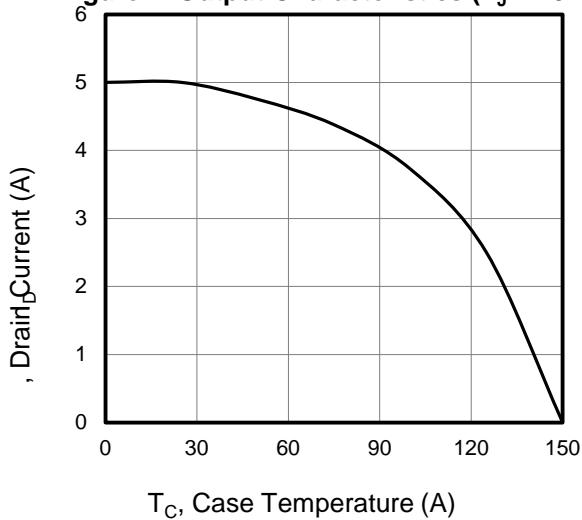
**Notes**

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{\text{AS}} = 3\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25\text{ }^{\circ}\text{C}$
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

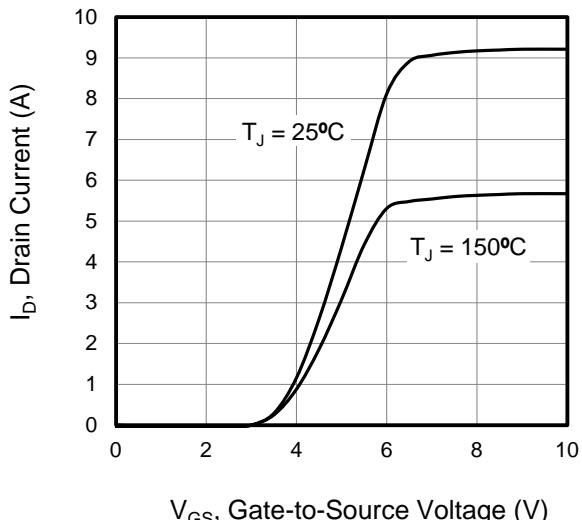
**Typical Characteristics**



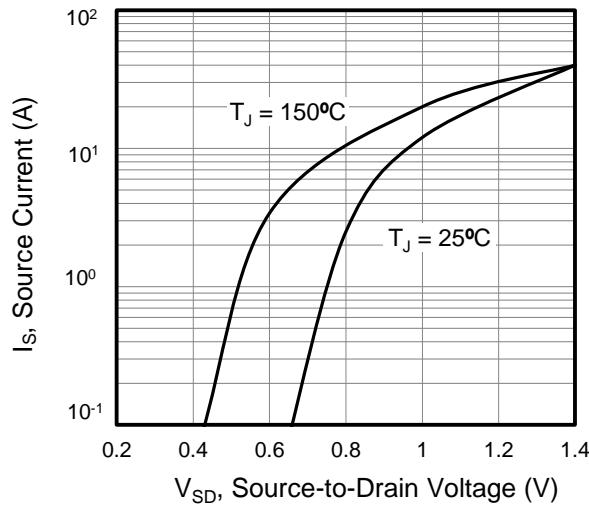
**Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )**



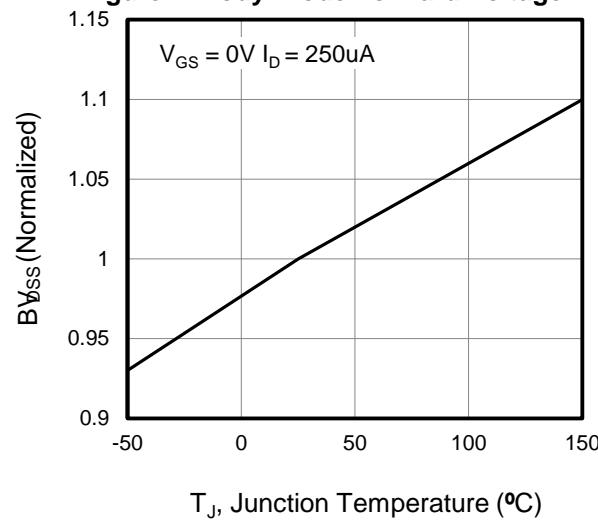
**Figure 3. Drain Current vs. Temperature**



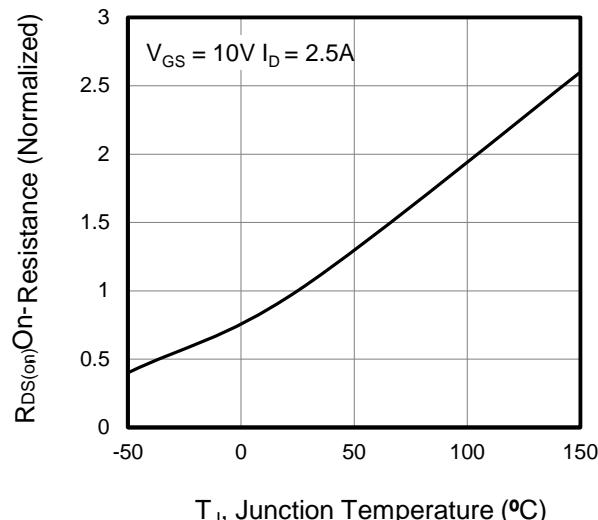
**Figure 5. Transfer Characteristics**



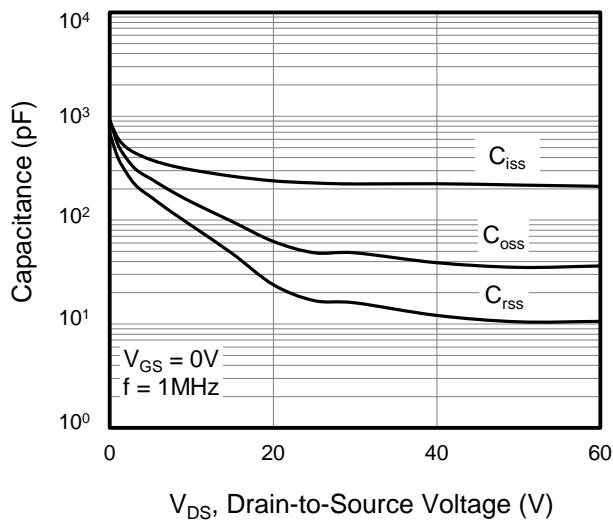
**Figure 2. Body Diode Forward Voltage**



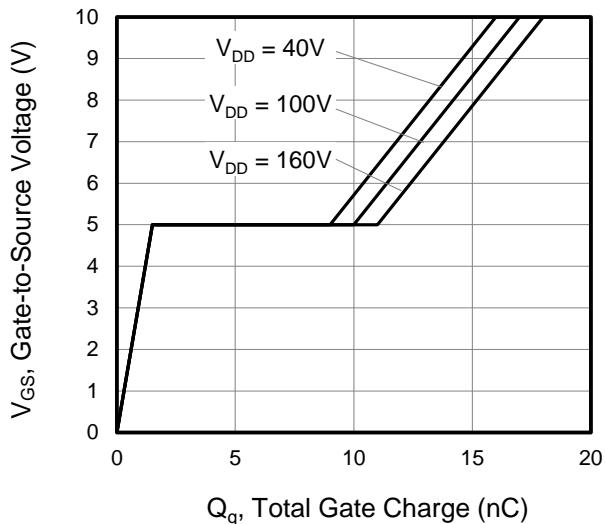
**Figure 4.  $BV_{DSS}$  Variation vs. Temperature**



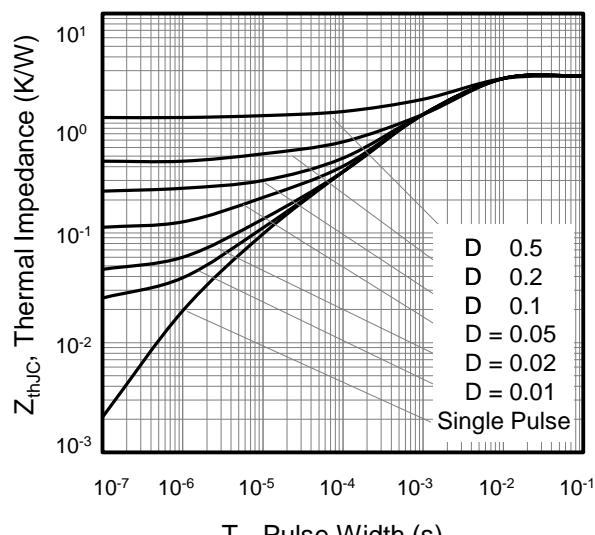
**Figure 6. On-Resistance vs. Temperature**



**Figure 7. Capacitance**



**Figure 8. Gate Charge**



**Figure 10. Transient Thermal Impedance**

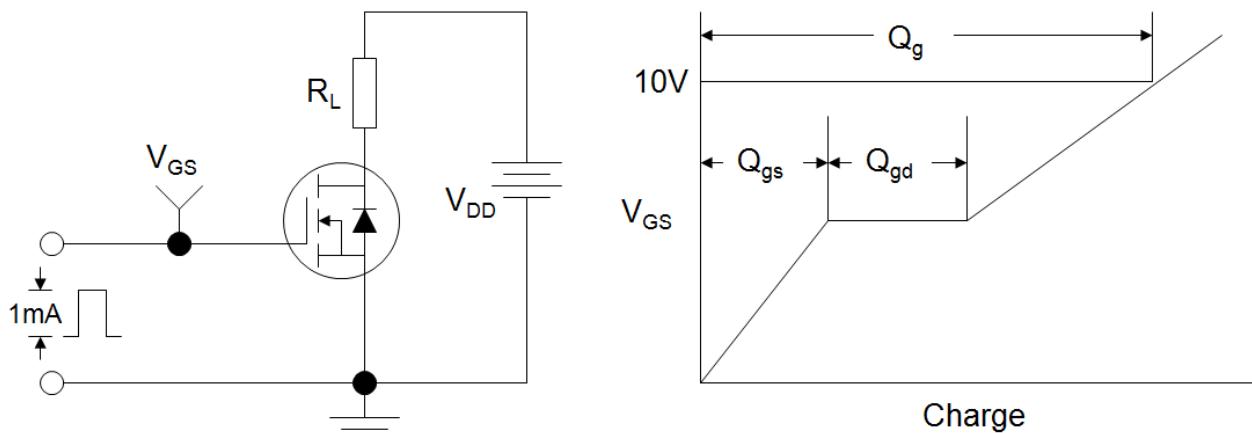


Figure A: Gate Charge Test Circuit and Waveform

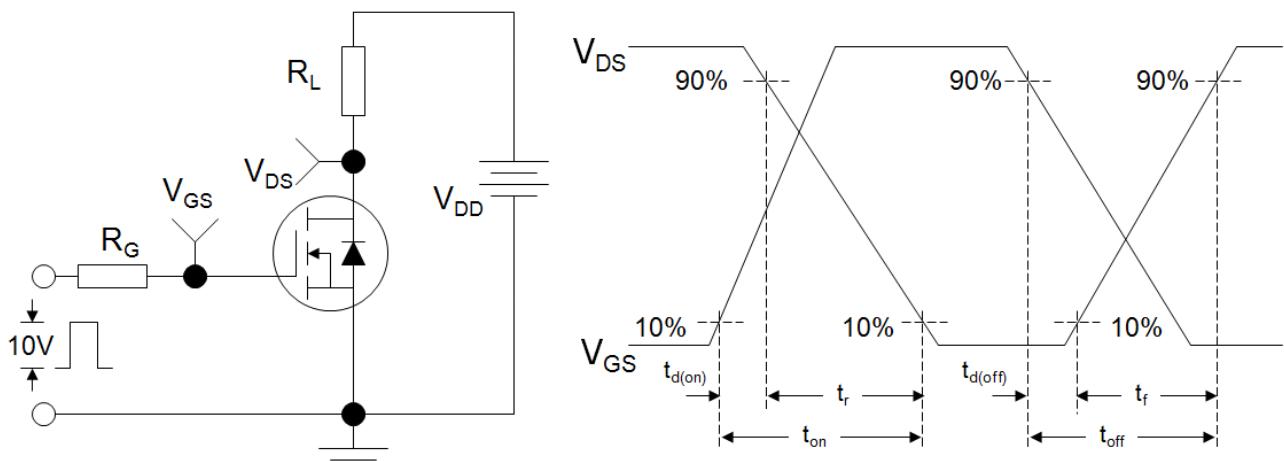


Figure B: Resistive Switching Test Circuit and Waveform

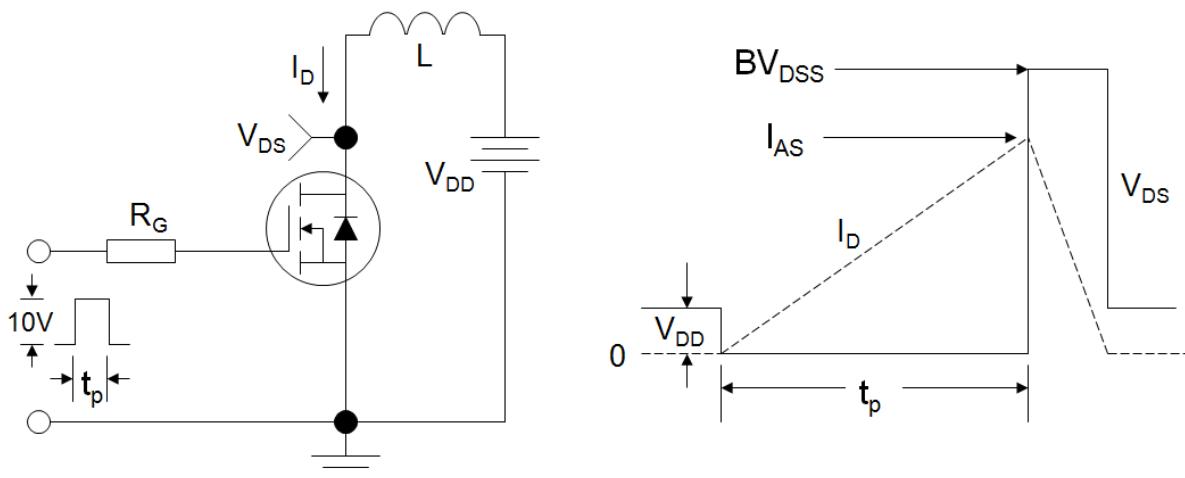
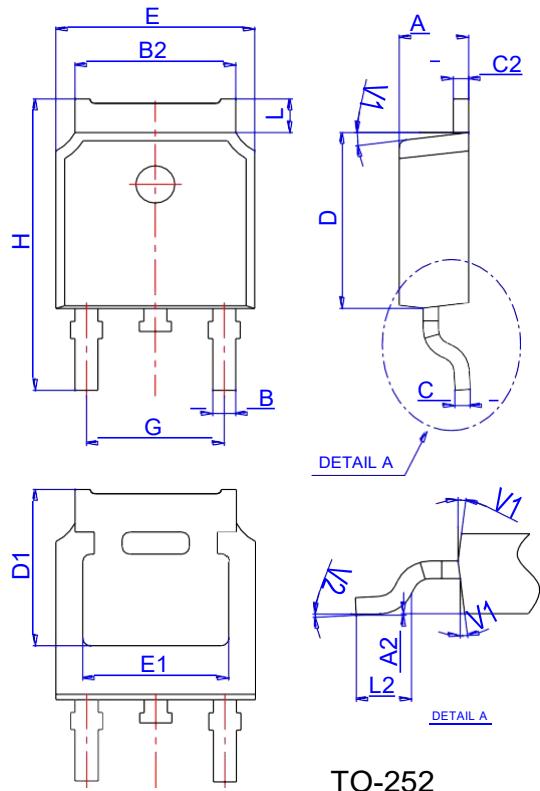


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

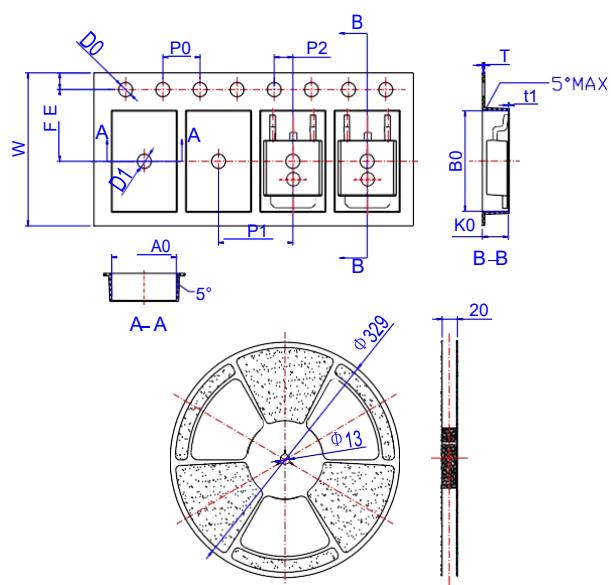
## Package Mechanical Data



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583